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Kathleen A. Manczuk
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Appl. No. : 10/803,464
Applicants : Noquil, et. al.
Filed : March 18, 2004 Art Unit: 2826
Title : MULTI-FLIP CHIP ON LEAD FRAME ON OVER MOLDED IC PACKAGE AND METHOD OF ASSEMBLY
Examiner : Tuan Quach
Docket No. : 3016271 US01
Customer No. : 44,331

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RESPONSE TO OFFICE ACTION

Sir:

Responsive to the October 5, 2005 Office Action, Applicants submit the following Amendment:

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 6 of this paper.